

MATERIALS AND FINISHES

BODY: ZINC ALLOY  
PLATED NICKEL

CENTER CONTACT: PHOSPHOR BRONZE  
PLATED GOLD

INSULATOR: PBT

HOUSING: LCP  
COLOR NATURAL

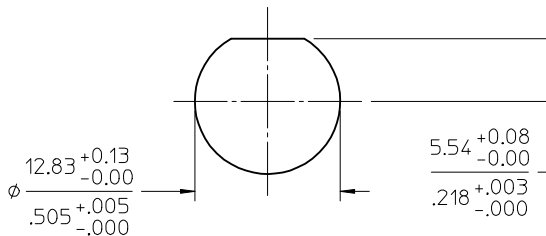
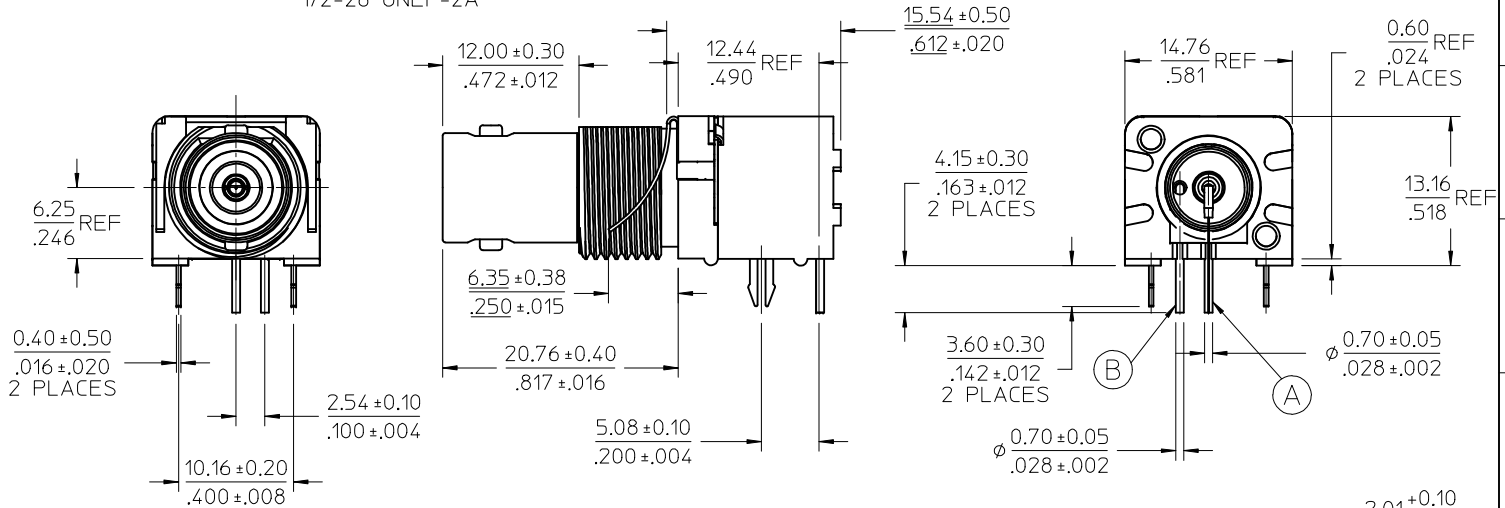
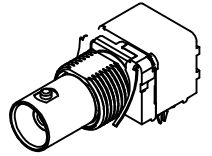
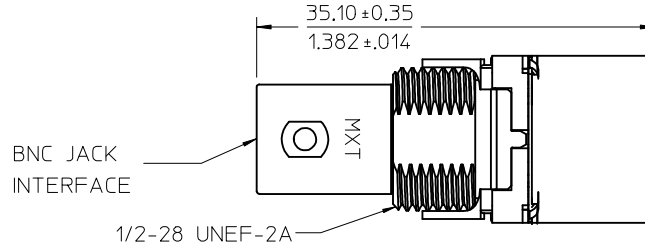
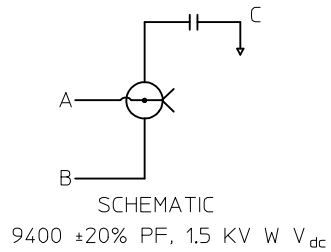
SOLDER TAIL: COPPER OVER STEEL WIRE  
PLATED TIN

FRONT/REAR CLIP: PHOSPHOR BRONZE  
PLATED NICKEL

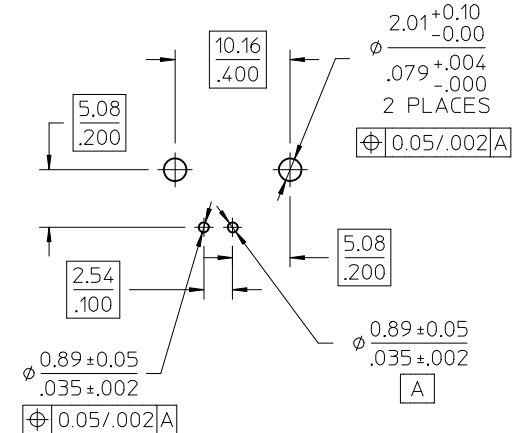
CHIP CAPACITOR: MULTILAYER CERAMIC

BOARD LOCK CLIP: PHOSPHOR BRONZE  
PLATED TIN

PACKAGING: BY TRAY



RECOMMENDED MOUNTING HOLE  
RECOMMENDED MOUNTING TORQUE:  
0.56 N-m(5.00 IN-LBS)  
PANEL THICKNESS: 5.5 (.217) MAX



RECOMMENDED PCB LAYOUT

PART # 73100-0166

PS-89675-1030

ELECTRO/MECH PERFORM.

SPECIFICATION

DESCRIPTION

CHG: ADD PACKAGING PER RF15-E224  
EC NO: URF2015-0673  
DRW/CWE102 2015/05/28  
CHKD:  
APPR: YCHENG 2015/06/04  
REV: B4

QUALITY SYMBOLS  
▽=0  
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)  
mm INCH  
4 PLACES ± --- ± ---  
3 PLACES ± --- ± ---  
2 PLACES ± --- ± ---  
1 PLACE ± --- ± ---  
ANGULAR ± 2 °  
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE MM/IN  
DRAWN BY JW IENER DATE 2013/05/08  
CHECKED BY SSS DATE 2013/05/08  
APPROVED BY JW IENER DATE 2013/05/09  
MATERIAL NO.  
SIZE C  
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SCALE DESIGN UNITS METRIC  
TITLE BNC JACK R/A PCB TH FILTER 50 OHM HIGH TEMP BNC-J/RA/PCB EWR-1088  
THIRD ANGLE PROJECTION  
MOLEX MOLEX INCORPORATED  
DOCUMENT NO. SD-73100-0166  
SHEET NO. 1 OF 1